



Applicant:

Luetzen, et al.

Docket No.:

INF115

Serial No.:

10/721,225

Art Unit:

1763

Filed:

November 26, 2003

Examiner:

George A. Goudreau

For:

Method and Structures for Increasing the Structure Density and the Storage

Capacitance in a Semiconductor Wafer

Certificate of Mailing via First Class Mail (37 C.F.R. § 1.8(a))

Date of Deposit:

August 14, 2006

I hereby certify that the below listed correspondence is being deposited with the United States Postal Service on the date indicated above as first class mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P. O. Box 1450, Alexandria, VA 22313-1450.

Certificate of Mailing via First Class Mail (1 page) Amendment (21 pages) Replacement Drawing Sheets (3 pages) Return Postcard

Respectfully submitted,

y Engeldabl

Kristy Engeldahl Legal Assistant

Slater & Matsil, L.L.P. 17950 Preston Rd., Suite 1000 Dallas, TX 75252

Tel: 972-732-1001 Fax: 972-732-9218